

PATENT

Atty Docket No.: 200315473-1

App. Ser. No.: 10/697,974

IN THE CLAIMS:

Please find below a listing of all of the pending claims. The statuses of the claims are set forth in parentheses.

1. (Currently amended) A system for delivering material onto a substrate, said system comprising:

a jetting assembly configured to deliver the material to the substrate as droplets;
comprising:

~~a reservoir containing the material, said reservoir having a nozzle through which the material is expelled from the reservoir;~~

~~an arcuate section positioned between the reservoir and the nozzle, wherein the material is configured to travel from the reservoir, through the arcuate section, and through the nozzle;~~

~~a means for applying pressure on the material contained in the reservoir, wherein the material is expelled from the reservoir through application of pressure by the means for applying pressure to thereby create a column of the material from the nozzle; and~~

~~a means for producing pressure modulations located proximate the nozzle, the means for producing pressure modulations being configured to substantially regulate formation of droplets from the column of the material;~~

~~a charging ring, wherein said droplets are configured to pass through the charging ring, and wherein the charging ring is configured to induce an electrical charge to selective ones of the droplets; [[and]]~~

~~one or more deflection plates for altering a trajectory of the charged droplets;~~

~~a support plate configured to support the substrate; and~~

PATENT

Atty Docket No.: 200315473-1

App. Ser. No.: 10/697,974

an electrostatic potential delivery device for delivering electrostatic potential to the support plate, wherein delivery of electrostatic potential to the support plate operates to vary the velocities at which the droplets impact the substrate.

2. (Currently amended) The system according to claim [[1]]3, wherein said arcuate section is configured to substantially prevent drying of the material in the nozzle.

3. (Currently amended) The system according to claim 1, the jetting assembly further comprising:

a reservoir containing the material, said reservoir having a nozzle through which the material is expelled from the reservoir;

an arcuate section positioned between the reservoir and the nozzle, wherein the material is configured to travel from the reservoir, through the arcuate section, and through the nozzle;

means for applying pressure on the material contained in the reservoir, wherein the material is expelled from the reservoir through application of pressure by the means for applying pressure to thereby create a column of the material from the nozzle; and

means for producing pressure modulations located proximate the nozzle, the means for producing pressure modulations being configured to substantially regulate formation of droplets from the column of the material~~a support plate configured to support one or both of the substrate and the jetting assembly.~~

PATENT

Atty Docket No.: 200315473-1

App. Ser. No.: 10/697,974

4. (Currently amended) The system according to claim ~~[[3]]~~1, wherein said support plate is configured to move in two or more dimensions to thereby move the substrate.

5. (Cancelled).

6. (Currently amended) The system according to claim ~~[[1]]~~3, further comprising:
a collection plate positioned between the one or more deflection plates and the substrate, said collection plate being configured to receive unwanted droplets, and wherein said collection plate is configured to direct received droplets to at least one of a waste area and the reservoir.

7. (Original) The system according to claim 6, wherein the one or more deflection plates are configured to alter the trajectories of unwanted droplets into the collection plate.

8. (Original) The system according to claim 1, wherein the one or more deflection plates are configured to alter the trajectories of the droplets to various sections of the substrate.

9. (Currently amended) The system according to claim ~~[[1]]~~3, further comprising:
a heating mechanism configured to supply heat to the material contained in the reservoir.

PATENT

Atty Docket No.: 200315473-1
App. Ser. No.: 10/697,974

10. (Original) The system according to claim 1, wherein the material comprises one or more of a semiconductor material, a metal, a dielectric, a passivation material, a protective coating material, an etchant, a dopant, and a reactant.

11. (Currently amended) The system according to claim [[1]]3, wherein the reservoir comprises a re-filling device configured to enable material to be inserted into the reservoir.

12. (Currently amended) The system according to claim [[1]]3, wherein the reservoir comprises a separate component and wherein the reservoir is separately replaceable.

13. (Currently amended) The system according to claim [[1]]3, further comprising:
a controller for controlling the means for applying pressure, the means for producing pressure modulations, the charging ring and the deflection plates;

14. (Currently amended) The system according to claim [[1]]3, wherein the means for producing pressure modulations comprises a PZT transducer.

15. (Currently amended) The system according to claim [[1]]3, further comprising:
a plurality of jetting assemblies;
a plurality of charging rings, wherein droplets from the plurality of jetting assemblies are configured to pass through respective ones of the plurality of charging rings; and
a plurality of deflection plates for altering the trajectories of the droplets from respective ones of the jetting assemblies.

PATENT

Atty Docket No.: 200315473-1

App. Ser. No.: 10/697,974

16. (Original) The system according to claim 15, wherein the plurality of jetting assemblies contain different materials with respect to each other.
17. (Original) The system according to claim 15, wherein the plurality of jetting assemblies are positioned to substantially simultaneously deposit material onto the substrate.
18. (Currently amended) A method for depositing a material onto a substrate, said method comprising:
- applying a pressure onto a material located in a reservoir, wherein said pressure causes the material to flow ~~through a arcuate section and~~ out of a nozzle in a fluid column;
 - creating pressure modulation through the fluid column to control formation of droplets from the fluid column, wherein the droplets travel along a flight path from the fluid column;
 - electrically charging one or more of the droplets; ~~[[and]]~~
 - depositing the one or more droplets onto the substrate;
 - determining whether a velocity at which the one or more droplets are deposited onto the substrate is to be altered prior to the step of depositing the one or more droplets onto the substrate; and
 - altering the velocities of the one or more droplets in response to a determination that the velocities at which the one or more droplets are deposited onto the substrate are to be altered ~~varying the flight path of at least one of the one or more charged droplets.~~

PATENT

Atty Docket No.: 200315473-1

App. Ser. No.: 10/697,974

19. (Currently amended) The method according to claim ~~[[18]]~~26, wherein the step of varying the flight path of at least one of the one or more charged droplets comprises inducing an electrostatic potential on the at least one of the one or more charged droplets to vary the flight path.

20. (Currently amended) The method according to claim ~~[[18]]~~26, further comprising:

determining whether at least one of the one or more charged droplets are to be discarded; and

wherein the step of varying the flight path of at least one of the one or more charged droplets comprises varying the flight path of one or more charged droplets to be discarded to direct the one or more charged droplets to be discarded to a collection plate.

21. (Currently amended) The method according to claim ~~[[18]]~~26, wherein the step of varying the flight path of at least one of the one or more charged droplets comprises varying the flight path of at least one of the one or more charged droplets having a charge/mass ratio falling outside of a predetermined charge/mass ratio range.

22. (Original) The method according to claim 18 further comprising: